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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	86
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12g128amllr

Chapter 24
16 KByte Flash Module (S12FTMRG16K1V1)

Chapter 25
32 KByte Flash Module (S12FTMRG32K1V1)

[1] The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

1.8.1.3 Pinout 48-Pin LQFP/QFN

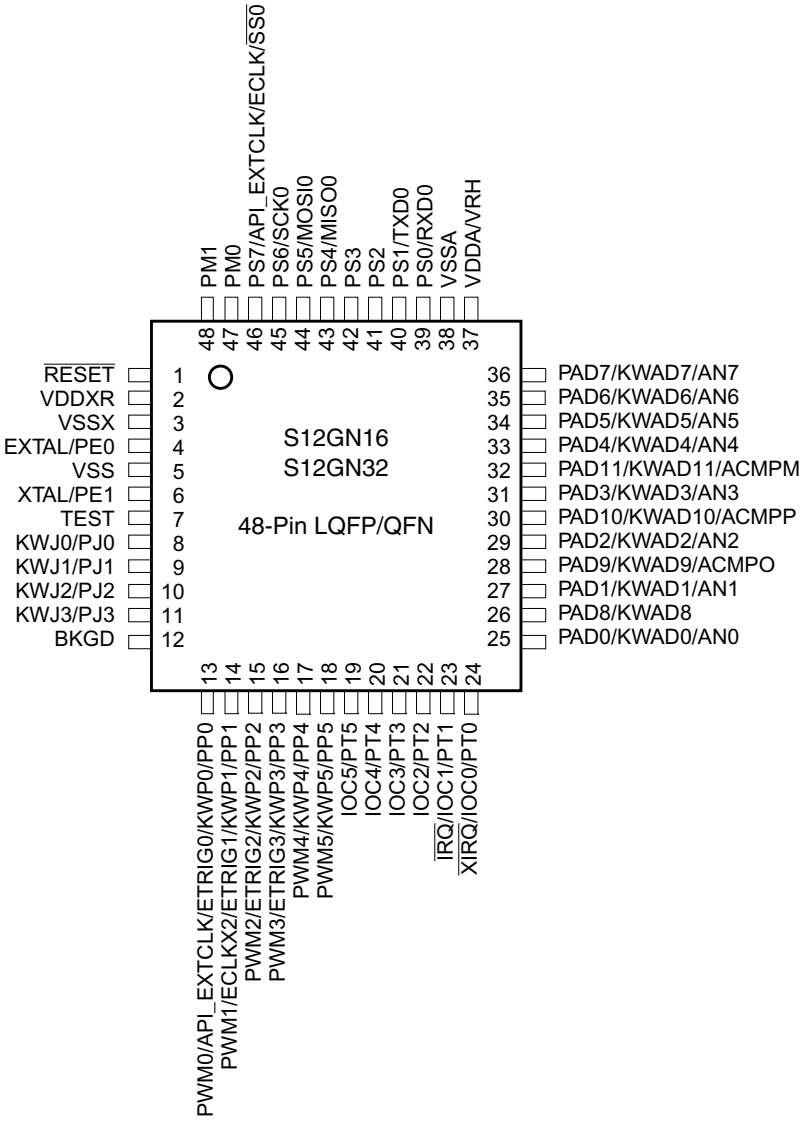

Figure 1-5. 48-Pin LQFP/QFN Pinout for S12GN16 and S12GN32

1.8.4 S12G48 and S12G64

1.8.4.1 Pinout 32-Pin LQFP

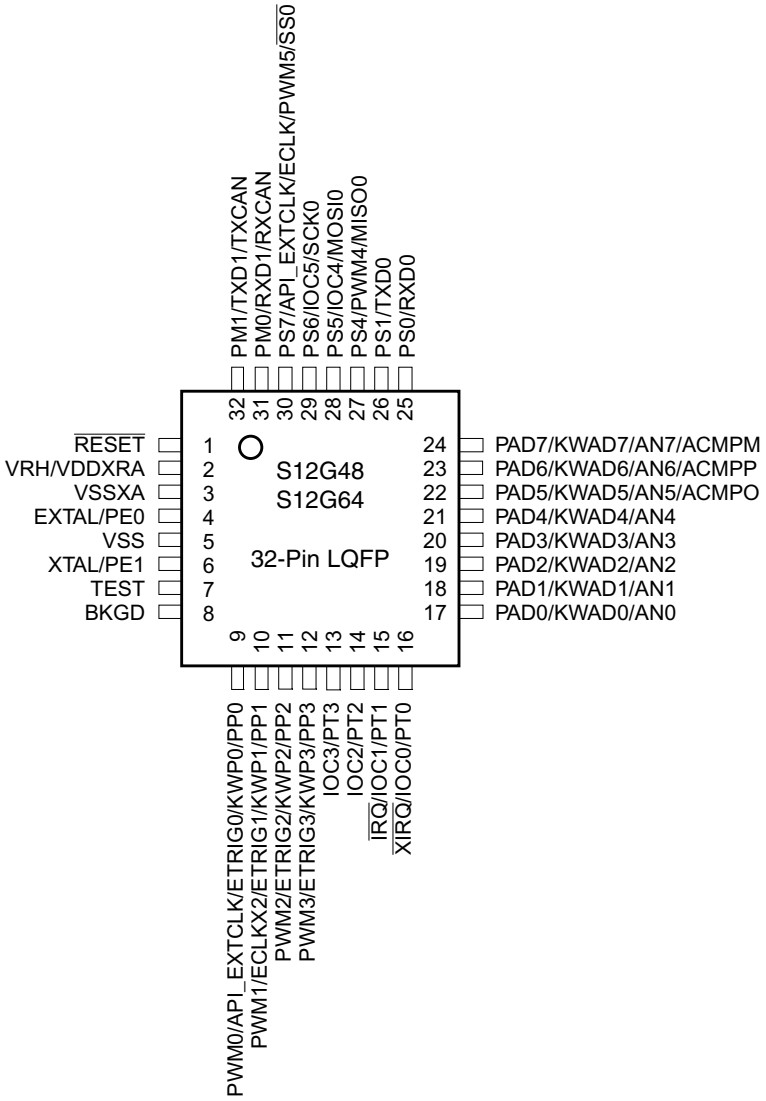

Figure 1-10. 32-Pin LQFP Pinout for S12G48 and S12G64

Table 1-15. 32-Pin LQFP Pinout for S12G48 and S12G64

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func		CTRL	Reset State
1	RESET	—	—	—	—	V_{DDX}	PULLUP	

Table 1-16. 48-Pin LQFP Pinout for S12G48 and S12G64

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func		CTRL	Reset State
28	PAD9	KWAD9	AN9	ACMPO	—	V_{DDA}	PER0AD/PPS0AD	Disabled
29	PAD2	KWAD2	AN2	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
30	PAD10	KWAD10	AN10	ACMPP		V_{DDA}	PER0AD/PPS0AD	Disabled
31	PAD3	KWAD3	AN3	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
32	PAD11	KWAD11	AN11	ACMPM		V_{DDA}	PER0AD/PPS0AD	Disabled
33	PAD4	KWAD4	AN4	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
34	PAD5	KWAD5	AN5	—	—	V_{DDA}	PER1AD/PPS0AD	Disabled
35	PAD6	KWAD6	AN6	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
36	PAD7	KWAD7	AN7	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
37	VDDA	VRH	—	—	—	—	—	—
38	VSSA	—	—	—	—	—	—	—
39	PS0	RXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
40	PS1	TXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
41	PS2	RXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
42	PS3	TXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
43	PS4	MISO0	—	—	—	V_{DDX}	PERS/PPSS	Up
44	PS5	MOSI0	—	—	—	V_{DDX}	PERS/PPSS	Up
45	PS6	SCK0	—	—	—	V_{DDX}	PERS/PPSS	Up
46	PS7	API_EXTCLK	ECLK	$\overline{SS0}$	—	V_{DDX}	PERS/PPSS	Up
47	PM0	RXCAN	—	—	—	V_{DDX}	PERM/PPSM	Disabled
48	PM1	TXCAN	—	—	—	V_{DDX}	PERM/PPSM	Disabled

1 The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

Figure 10-2 shows a block diagram of the XOSCLCP.

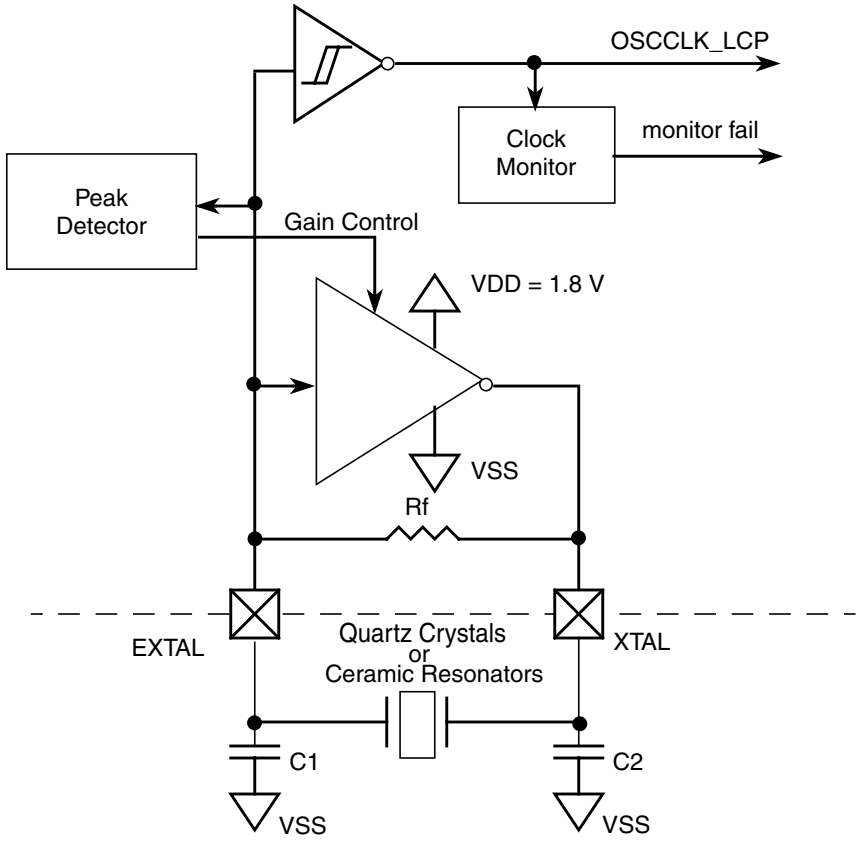

Figure 10-2. XOSCLCP Block Diagram

10.2 Signal Description

This section lists and describes the signals that connect off chip.

10.2.1 $\overline{\text{RESET}}$

Pin $\overline{\text{RESET}}$ is an active-low bidirectional pin. As an input it initializes the MCU asynchronously to a known start-up state. As an open-drain output it indicates that an MCU-internal reset has been triggered.

10.2.2 EXTAL and XTAL

These pins provide the interface for a crystal to control the internal clock generator circuitry. EXTAL is the input to the crystal oscillator amplifier. XTAL is the output of the crystal oscillator amplifier. If XOSCLCP is enabled, the MCU internal OSCCLK_LCP is derived from the EXTAL input frequency. If OSCE=0, the EXTAL pin is pulled down by an internal resistor of approximately 200 kΩ and the XTAL pin is pulled down by an internal resistor of approximately 700 kΩ.

NOTE

Freescale recommends an evaluation of the application board and chosen resonator or crystal by the resonator or crystal supplier.
The loop controlled circuit (XOSCLCP) is not suited for overtone resonators and crystals.

10.2.3 VDDR — Regulator Power Input Pin

Pin V_{DDR} is the power input of IVREG. All currents sourced into the regulator loads flow through this pin.

An off-chip decoupling capacitor (100 nF...220 nF, X7R ceramic) between V_{DDR} and V_{SS} can smooth ripple on V_{DDR}.

10.2.4 VSS — Ground Pin

V_{SS} must be grounded.

10.2.5 VDDA, VSSA — Regulator Reference Supply Pins

Pins V_{DDA} and V_{SSA} are used to supply the analog parts of the regulator.
Internal precision reference circuits are supplied from these signals.

An off-chip decoupling capacitor (100 nF...220 nF, X7R ceramic) between V_{DDA} and V_{SSA} can improve the quality of this supply.

10.2.6 VDDX, VSSX— Pad Supply Pins

This supply domain is monitored by the Low Voltage Reset circuit.

An off-chip decoupling capacitor (100 nF...220 nF, X7R ceramic) between VDDX and VSSX can improve the quality of this supply.

NOTE

Depending on the device package following device supply pins are maybe combined into one pin: VDDR, VDDX and VDDA.
Depending on the device package following device supply pins are maybe combined into one pin: VSS, VSSX and VSSA.
Please refer to the device Reference Manual for information if device supply pins are combined into one supply pin for certain packages and which supply pins are combined together.
An off-chip decoupling capacitor (100 nF...220 nF, X7R ceramic) between the combined supply pin pair can improve the quality of this supply.

15.1 Introduction

The ADC10B16C is a 16-channel, 10-bit, multiplexed input successive approximation analog-to-digital converter. Refer to device electrical specifications for ATD accuracy.

15.1.1 Features

- 8-, 10-bit resolution.
- Automatic return to low power after conversion sequence
- Automatic compare with interrupt for higher than or less/equal than programmable value
- Programmable sample time.
- Left/right justified result data.
- External trigger control.
- Sequence complete interrupt.
- Analog input multiplexer for 8 analog input channels.
- Special conversions for VRH, VRL, (VRL+VRH)/2.
- 1-to-16 conversion sequence lengths.
- Continuous conversion mode.
- Multiple channel scans.
- Configurable external trigger functionality on any AD channel or any of four additional trigger inputs. The four additional trigger inputs can be chip external or internal. Refer to device specification for availability and connectivity.
- Configurable location for channel wrap around (when converting multiple channels in a sequence).

15.4 Functional Description

The ADC10B16C consists of an analog sub-block and a digital sub-block.

15.4.1 Analog Sub-Block

The analog sub-block contains all analog electronics required to perform a single conversion. Separate power supplies VDDA and VSSA allow to isolate noise of other MCU circuitry from the analog sub-block.

15.4.1.1 Sample and Hold Machine

The Sample and Hold Machine controls the storage and charge of the sample capacitor to the voltage level of the analog signal at the selected ADC input channel.

During the sample process the analog input connects directly to the storage node.

The input analog signals are unipolar and must be within the potential range of VSSA to VDDA.

During the hold process the analog input is disconnected from the storage node.

15.4.1.2 Analog Input Multiplexer

The analog input multiplexer connects one of the 16 external analog input channels to the sample and hold machine.

15.4.1.3 Analog-to-Digital (A/D) Machine

The A/D Machine performs analog to digital conversions. The resolution is program selectable to be either 8 or 10 bits. The A/D machine uses a successive approximation architecture. It functions by comparing the sampled and stored analog voltage with a series of binary coded discrete voltages.

By following a binary search algorithm, the A/D machine identifies the discrete voltage that is nearest to the sampled and stored voltage.

When not converting the A/D machine is automatically powered down.

Only analog input signals within the potential range of VRL to VRH (A/D reference potentials) will result in a non-railed digital output code.

15.4.2 Digital Sub-Block

This subsection describes some of the digital features in more detail. See Section 15.3.2, “Register Descriptions” for all details.

15.4.2.1 External Trigger Input

The external trigger feature allows the user to synchronize ATD conversions to an external event rather than relying only on software to trigger the ATD module when a conversion is about to take place. The external trigger signal (out of reset ATD channel 15, configurable in ATDCTL1) is programmable to be

18.1.3 Features

The basic features of the MSCAN are as follows:

- Implementation of the CAN protocol — Version 2.0A/B
  - — Standard and extended data frames
  - — Zero to eight bytes data length
  - — Programmable bit rate up to 1 Mbps[1]
  - — Support for remote frames
- Five receive buffers with FIFO storage scheme
- Three transmit buffers with internal prioritization using a "local priority" concept
- Flexible maskable identifier filter supports two full-size (32-bit) extended identifier filters, or four 16-bit filters, or eight 8-bit filters
- Programmable wake-up functionality with integrated low-pass filter
- Programmable loopback mode supports self-test operation
- Programmable listen-only mode for monitoring of CAN bus
- Programmable bus-off recovery functionality
- Separate signalling and interrupt capabilities for all CAN receiver and transmitter error states (warning, error passive, bus-off)
- Programmable MSCAN clock source either bus clock or oscillator clock
- Internal timer for time-stamping of received and transmitted messages
- Three low-power modes: sleep, power down, and MSCAN enable
- Global initialization of configuration registers

18.1.4 Modes of Operation

For a description of the specific MSCAN modes and the module operation related to the system operating modes refer to Section 18.4.4, "Modes of Operation".

18.2 External Signal Description

The MSCAN uses two external pins.

NOTE

On MCUs with an integrated CAN physical interface (transceiver) the MSCAN interface is connected internally to the transceiver interface. In these cases the external availability of signals TXCAN and RXCAN is optional.

18.2.1 RXCAN — CAN Receiver Input Pin

RXCAN is the MSCAN receiver input pin.

1. Depending on the actual bit timing and the clock jitter of the PLL.

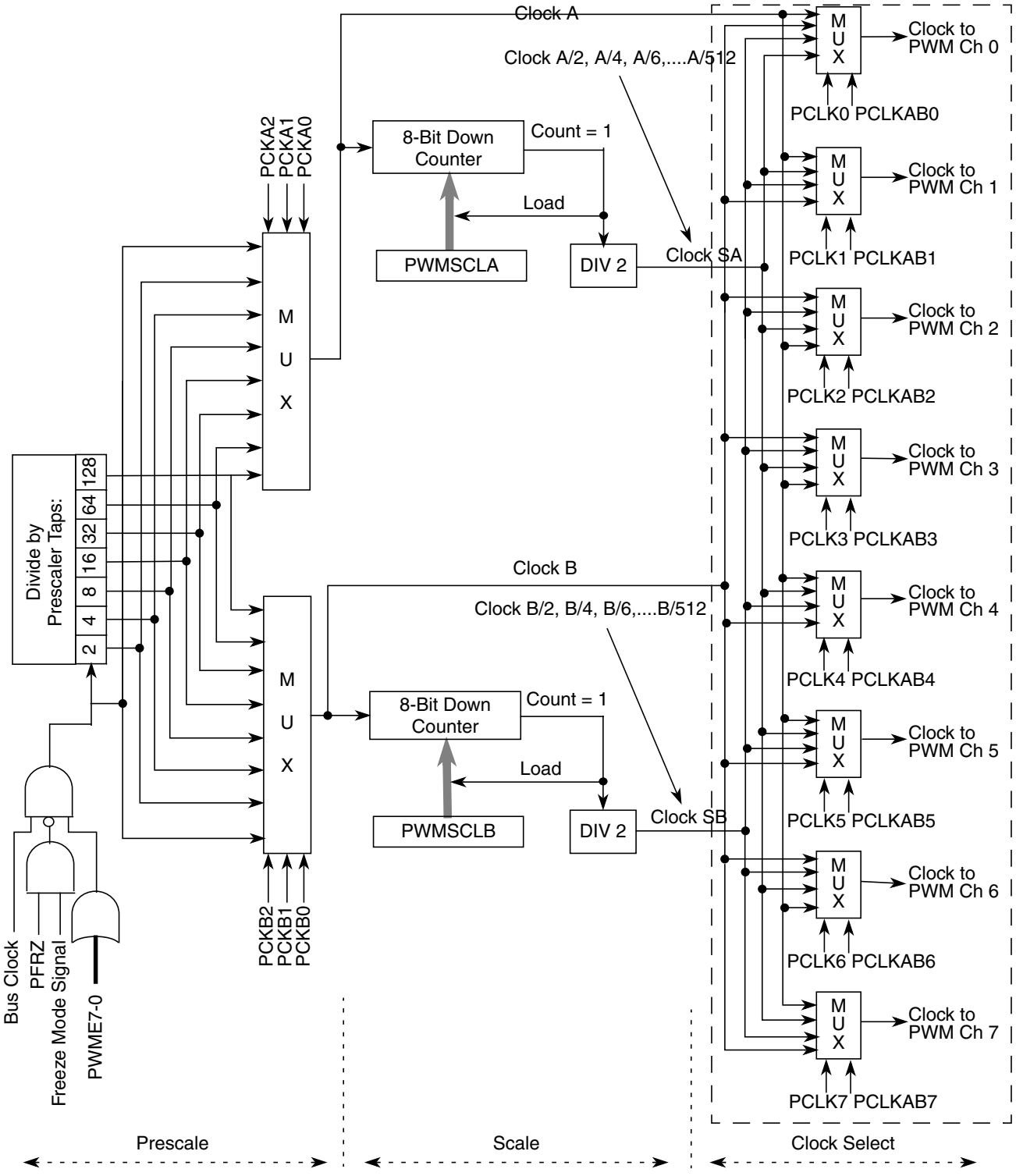

Figure 19-15. PWM Clock Select Block Diagram

20.4.5.5 LIN Transmit Collision Detection

This module allows to check for collisions on the LIN bus.

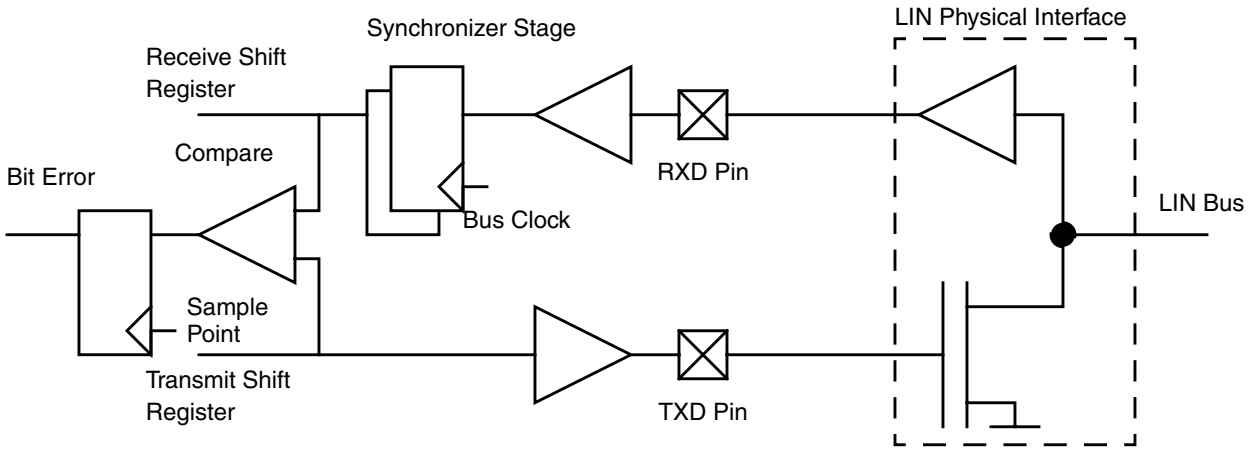

Figure 20-18. Collision Detect Principle

If the bit error circuit is enabled (BERRM[1:0] = 0:1 or = 1:0]), the error detect circuit will compare the transmitted and the received data stream at a point in time and flag any mismatch. The timing checks run when transmitter is active (not idle). As soon as a mismatch between the transmitted data and the received data is detected the following happens:

- The next bit transmitted will have a high level (TXPOL = 0) or low level (TXPOL = 1)
- The transmission is aborted and the byte in transmit buffer is discarded.
- the transmit data register empty and the transmission complete flag will be set
- The bit error interrupt flag, BERRIF, will be set.
- No further transmissions will take place until the BERRIF is cleared.

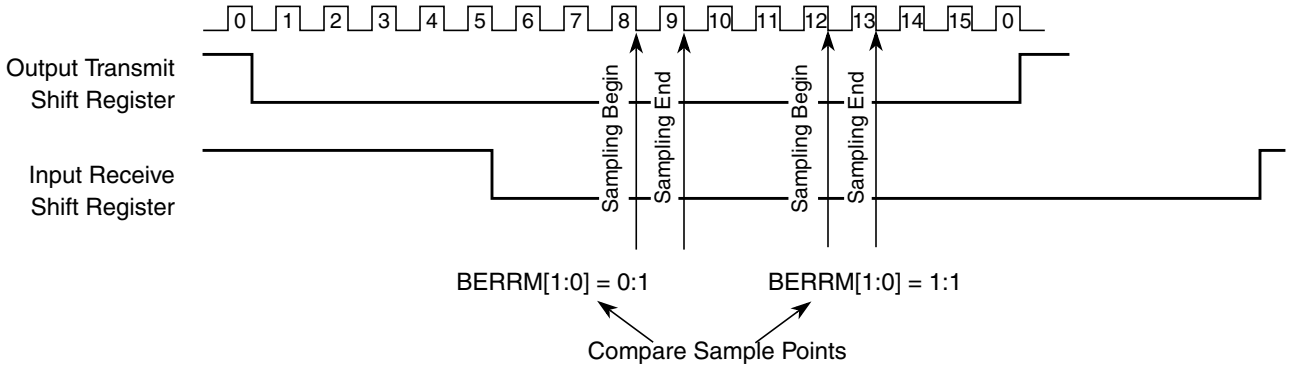

Figure 20-19. Timing Diagram Bit Error Detection

If the bit error detect feature is disabled, the bit error interrupt flag is cleared.

NOTE

The RXPOL and TXPOL bit should be set the same when transmission collision detect feature is enabled, otherwise the bit error interrupt flag may be set incorrectly.

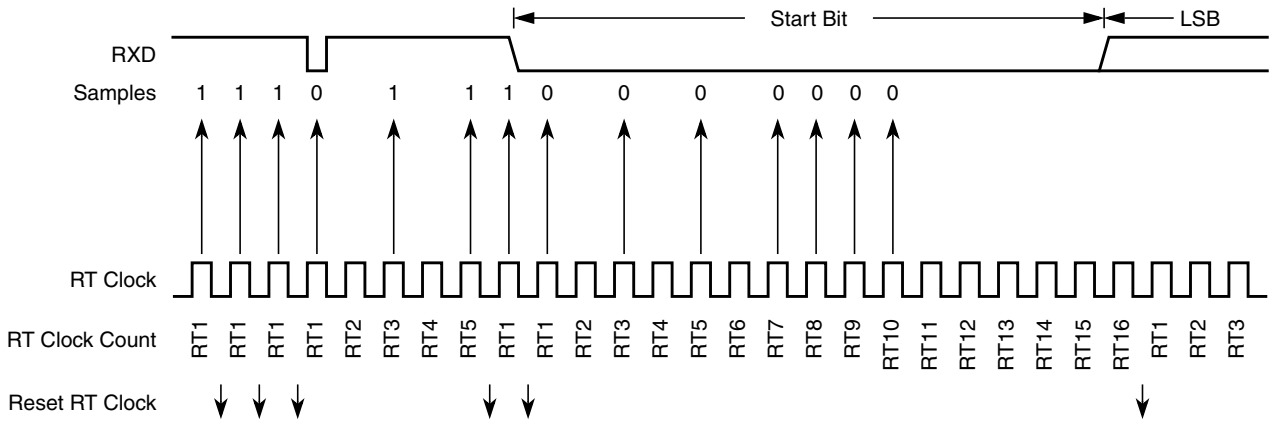

Figure 20-22. Start Bit Search Example 1

In Figure 20-23, verification sample at RT3 is high. The RT3 sample sets the noise flag. Although the perceived bit time is misaligned, the data samples RT8, RT9, and RT10 are within the bit time and data recovery is successful.

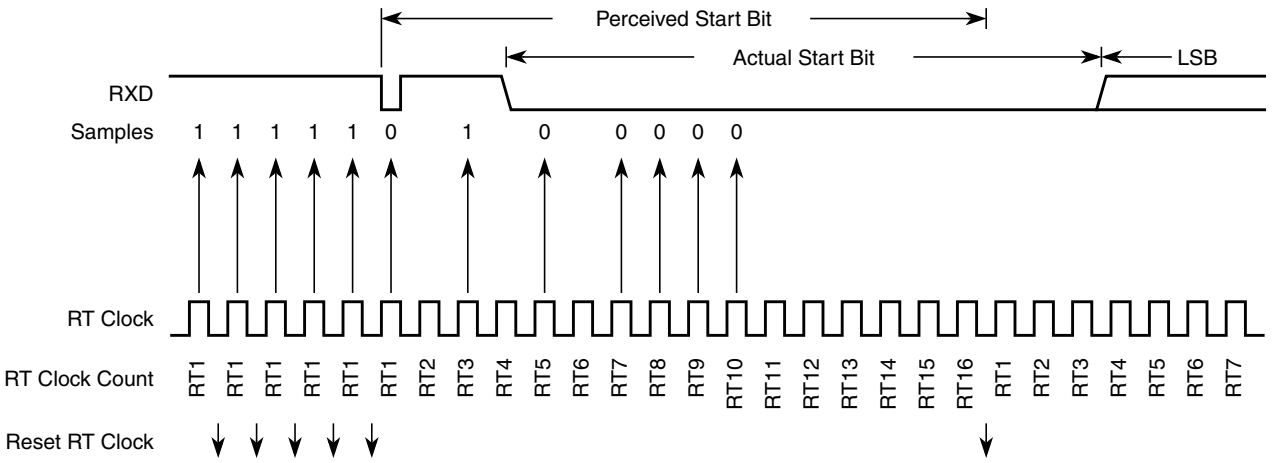

Figure 20-23. Start Bit Search Example 2

In Figure 20-24, a large burst of noise is perceived as the beginning of a start bit, although the test sample at RT5 is high. The RT5 sample sets the noise flag. Although this is a worst-case misalignment of perceived bit time, the data samples RT8, RT9, and RT10 are within the bit time and data recovery is successful.

- Double-buffered data register
- Serial clock with programmable polarity and phase
- Control of SPI operation during wait mode

21.1.3 Modes of Operation

The SPI functions in three modes: run, wait, and stop.

- Run mode

  This is the basic mode of operation.
- Wait mode

  SPI operation in wait mode is a configurable low power mode, controlled by the SPISWAI bit located in the SPICR2 register. In wait mode, if the SPISWAI bit is clear, the SPI operates like in run mode. If the SPISWAI bit is set, the SPI goes into a power conservative state, with the SPI clock generation turned off. If the SPI is configured as a master, any transmission in progress stops, but is resumed after CPU goes into run mode. If the SPI is configured as a slave, reception and transmission of data continues, so that the slave stays synchronized to the master.
- Stop mode

  The SPI is inactive in stop mode for reduced power consumption. If the SPI is configured as a master, any transmission in progress stops, but is resumed after CPU goes into run mode. If the SPI is configured as a slave, reception and transmission of data continues, so that the slave stays synchronized to the master.

For a detailed description of operating modes, please refer to Section 21.4.7, “Low Power Mode Options”.

21.1.4 Block Diagram

Figure 21-1 gives an overview on the SPI architecture. The main parts of the SPI are status, control and data registers, shifter logic, baud rate generator, master/slave control logic, and port control logic.

Module Base + 0x0005

	7	6	5	4	3	2	1	0
R W	TCNT7	TCNT6	TCNT5	TCNT4	TCNT3	TCNT2	TCNT1	TCNT0
Reset	0	0	0	0	0	0	0	0

Figure 23-11. Timer Count Register Low (TCNTL)

The 16-bit main timer is an up counter.

A full access for the counter register should take place in one clock cycle. A separate read/write for high byte and low byte will give a different result than accessing them as a word.

Read: Anytime

Write: Has no meaning or effect in the normal mode; only writable in special modes (test_mode = 1).

The period of the first count after a write to the TCNT registers may be a different size because the write is not synchronized with the prescaler clock.

23.3.2.6 Timer System Control Register 1 (TSCR1)

Module Base + 0x0006

	7	6	5	4	3	2	1	0
R	TEN	TSWAI	TSFRZ	TFFCA	PRNT	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 23-12. Timer System Control Register 1 (TSCR1)

Read: Anytime

Write: Anytime

Table 23-6. TSCR1 Field Descriptions

Field	Description
7 TEN	Timer Enable 0 Disables the main timer, including the counter. Can be used for reducing power consumption. 1 Allows the timer to function normally. If for any reason the timer is not active, there is no ÷64 clock for the pulse accumulator because the ÷64 is generated by the timer prescaler.
6 TSWAI	Timer Module Stops While in Wait 0 Allows the timer module to continue running during wait. 1 Disables the timer module when the MCU is in the wait mode. Timer interrupts cannot be used to get the MCU out of wait. TSWAI also affects pulse accumulator.

Table 26-24. FCCOB - NVM Command Mode (Typical Usage)

CCOBIX[2:0]	Byte	FCCOB Parameter Fields (NVM Command Mode)
010	HI	Data 0 [15:8]
	LO	Data 0 [7:0]
011	HI	Data 1 [15:8]
	LO	Data 1 [7:0]
100	HI	Data 2 [15:8]
	LO	Data 2 [7:0]
101	HI	Data 3 [15:8]
	LO	Data 3 [7:0]

26.3.2.12 Flash Reserved1 Register (FRSV1)

This Flash register is reserved for factory testing.

Offset Module Base + 0x000C

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 26-18. Flash Reserved1 Register (FRSV1)

All bits in the FRSV1 register read 0 and are not writable.

26.3.2.13 Flash Reserved2 Register (FRSV2)

This Flash register is reserved for factory testing.

Offset Module Base + 0x000D

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 26-19. Flash Reserved2 Register (FRSV2)

All bits in the FRSV2 register read 0 and are not writable.

26.3.2.14 Flash Reserved3 Register (FRSV3)

This Flash register is reserved for factory testing.

CAUTION

The FCLKDIV register should never be written while a Flash command is executing (CCIF=0).

Table 28-7. FCLKDIV Field Descriptions

Field	Description
7 FDIVLD	Clock Divider Loaded 0 FCLKDIV register has not been written since the last reset 1 FCLKDIV register has been written since the last reset
6 FDIVLCK	Clock Divider Locked 0 FDIV field is open for writing 1 FDIV value is locked and cannot be changed. Once the lock bit is set high, only reset can clear this bit and restore writability to the FDIV field in normal mode.
5–0 FDIV[5:0]	**Clock Divider Bits** — FDIV[5:0] must be set to effectively divide BUSCLK down to 1 MHz to control timed events during Flash program and erase algorithms. Table 28-8 shows recommended values for FDIV[5:0] based on the BUSCLK frequency. Please refer to Section 28.4.4, “Flash Command Operations,” for more information.

Table 28-8. FDIV values for various BUSCLK Frequencies

BUSCLK Frequency (MHz)		FDIV[5:0]	BUSCLK Frequency (MHz)		FDIV[5:0]
MIN[1]	MAX[2]		MIN[1]	MAX[2]	
1.0	1.6	0x00	16.6	17.6	0x10
1.6	2.6	0x01	17.6	18.6	0x11
2.6	3.6	0x02	18.6	19.6	0x12
3.6	4.6	0x03	19.6	20.6	0x13
4.6	5.6	0x04	20.6	21.6	0x14
5.6	6.6	0x05	21.6	22.6	0x15
6.6	7.6	0x06	22.6	23.6	0x16
7.6	8.6	0x07	23.6	24.6	0x17
8.6	9.6	0x08	24.6	25.6	0x18
9.6	10.6	0x09			
10.6	11.6	0x0A			
11.6	12.6	0x0B			
12.6	13.6	0x0C			
13.6	14.6	0x0D			
14.6	15.6	0x0E			
15.6	16.6	0x0F			

1 BUSCLK is Greater Than this value.

2 BUSCLK is Less Than or Equal to this value.

Trying to alter data in any protected area in the P-Flash memory will result in a protection violation error and the FPVIOL bit will be set in the FSTAT register. The block erase of a P-Flash block is not possible if any of the P-Flash sectors contained in the same P-Flash block are protected.

Table 28-17. FPROT Field Descriptions

Field	Description
7 FPOPEN	**Flash Protection Operation Enable** — The FPOPEN bit determines the protection function for program or erase operations as shown in Table 28-18 for the P-Flash block. 0 When FPOPEN is clear, the FPHDIS and FPLDIS bits define unprotected address ranges as specified by the corresponding FPHS and FPLS bits 1 When FPOPEN is set, the FPHDIS and FPLDIS bits enable protection for the address range specified by the corresponding FPHS and FPLS bits
6 RNV[6]	**Reserved Nonvolatile Bit** — The RNV bit should remain in the erased state for future enhancements.
5 FPHDIS	**Flash Protection Higher Address Range Disable** — The FPHDIS bit determines whether there is a protected/unprotected area in a specific region of the P-Flash memory ending with global address 0x3_FFFF. 0 Protection/Unprotection enabled 1 Protection/Unprotection disabled
4–3 FPHS[1:0]	**Flash Protection Higher Address Size** — The FPHS bits determine the size of the protected/unprotected area in P-Flash memory as shown inTable 28-19. The FPHS bits can only be written to while the FPHDIS bit is set.
2 FPLDIS	**Flash Protection Lower Address Range Disable** — The FPLDIS bit determines whether there is a protected/unprotected area in a specific region of the P-Flash memory beginning with global address 0x3_8000. 0 Protection/Unprotection enabled 1 Protection/Unprotection disabled
1–0 FPLS[1:0]	**Flash Protection Lower Address Size** — The FPLS bits determine the size of the protected/unprotected area in P-Flash memory as shown in Table 28-20. The FPLS bits can only be written to while the FPLDIS bit is set.

Table 28-18. P-Flash Protection Function

FPOPEN	FPHDIS	FPLDIS	Function[1]
1	1	1	No P-Flash Protection
1	1	0	Protected Low Range
1	0	1	Protected High Range
1	0	0	Protected High and Low Ranges
0	1	1	Full P-Flash Memory Protected
0	1	0	Unprotected Low Range
0	0	1	Unprotected High Range
0	0	0	Unprotected High and Low Ranges

[1] For range sizes, refer to Table 28-19 and Table 28-20.

Table 30-41. Program P-Flash Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 101 at command launch
		Set if command not available in current mode (see Table 30-27)
		Set if an invalid global address [17:0] is supplied see Table 30-3)
		Set if a misaligned phrase address is supplied (global address [2:0] != 000)
	FPVIOL	Set if the global address [17:0] points to a protected area
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

30.4.6.6 Program Once Command

The Program Once command restricts programming to a reserved 64 byte field (8 phrases) in the nonvolatile information register located in P-Flash. The Program Once reserved field can be read using the Read Once command as described in Section 30.4.6.4. The Program Once command must only be issued once since the nonvolatile information register in P-Flash cannot be erased. The Program Once command must not be executed from the Flash block containing the Program Once reserved field to avoid code runaway.

Table 30-42. Program Once Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters	
000	0x07	Not Required
001	Program Once phrase index (0x0000 - 0x0007)	
010	Program Once word 0 value	
011	Program Once word 1 value	
100	Program Once word 2 value	
101	Program Once word 3 value	

Upon clearing CCIF to launch the Program Once command, the Memory Controller first verifies that the selected phrase is erased. If erased, then the selected phrase will be programmed and then verified with read back. The CCIF flag will remain clear, setting only after the Program Once operation has completed.

The reserved nonvolatile information register accessed by the Program Once command cannot be erased and any attempt to program one of these phrases a second time will not be allowed. Valid phrase index values for the Program Once command range from 0x0000 to 0x0007. During execution of the Program Once command, any attempt to read addresses within P-Flash will return invalid data.

1 The values for thermal resistance are achieved by package simulations

2 Per JEDEC JESD51-2 with the single layer board (JESD51-3) horizontal.J

3 Per JEDEC JESD51-6 with the board (JESD51-7) horizontal.

4 .Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured in simulation on the top surface of the board near the package.

5 Thermal resistance between the die and the case top surface as measured in simulation by the cold plate method (MIL SPEC-883 Method 1012.1).

6 Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2. Ψ_{JT} is a useful value to use to estimate junction temperature in a steady state customer enviroment.

A.2 I/O Characteristics

This section describes the characteristics of all I/O pins except EXTAL, XTAL, TEST, and supply pins.

Table A-6. 3.3-V I/O Characteristics (Junction Temperature From –40°C To +150°C)

Conditions are 3.15 V < V_{DD35} < 3.6 V junction temperature from –40°C to +150°C, unless otherwise noted I/O Characteristics for all I/O pins except EXTAL, XTAL,TEST and supply pins.							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Input high voltage	V_{IH}	$0.65*V_{DD35}$	—	—	V
2	T	Input high voltage	V_{IH}	—	—	V_{DD35}+0.3	V
3	P	Input low voltage	V_{IL}	—	—	$0.35*V_{DD35}$	V
4	T	Input low voltage	V_{IL}	V_{SS35} – 0.3	—	—	V
5	C	Input hysteresis	V_{HYS}	$0.06*V_{DD35}$	—	$0.3*V_{DD35}$	mV
6	P	Input leakage current (pins in high impedance input mode)[1] V_{in} = V_{DD35} or V_{SS35} +125°C to < T_J < 150°C +105°C to < T_J < 125° –40°C to < T_J < 105°C	I_{in}	 -1 -0.5 -0.4	 — — —	 1 0.5 0.4	µA
7	P	Output high voltage (pins in output mode) I_{OH} = –1.75 mA	V_{OH}	V_{DD35}-0.4	—	—	V
8	C	Output low voltage (pins in output mode) I_{OL} = +1.75 mA	V_{OL}	—	—	0.4	V
9	P	Internal pull up device current V_{IH} min > input voltage > V_{IL} max	I_{PUL}	-1	—	–70	µA
10	P	Internal pull down device current V_{IH} min > input voltage > V_{IL} max	I_{PDH}	1	—	70	µA
11	D	Input capacitance	C_{in}	—	7	—	pF
12	T	Injection current[2] Single pin limit Total device limit, sum of all injected currents	 I_{ICS} I_{ICP}	 –2.5 –25	—	 2.5 25	mA

1 Maximum leakage current occurs at maximum operating temperature. Current decreases by approximately one-half for each 8°C to 12 C in the temperature range from 50°C to 125°C.

2 Refer to Section A.1.4, “Current Injection” for more details